Amendments to the Claims

The listing of claims below will replace all prior versions and listings of claims in the application.

1. (Canceled)

2. (Previously Presented) A method for producing, on a substrate, an electronic component with closely adjacent electrodes, the method comprising:

depositing a first metal layer onto the substrate;

structuring a first photo lacquer on a surface of the first metal layer, wherein a portion of the surface of the first metal layer does not have the first photo lacquer thereon;

etching the portion of the surface of the first metal layer not having the first photo lacquer;

undercut etching the first metal layer so that an overhang is defined by the first photo lacquer;

exposing, to a metal vapor, a surface of the first photo lacquer and an exposed portion of the substrate where the first metal layer was etched away so that a second metal layer is formed on the surface of the first photo lacquer and the exposed portion of the substrate where the first metal layer was etched away except in a space between the overhang and the substrate; and

removing both the first photo lacquer and the second metal layer from the surface of the first photo lacquer.

3. (Canceled)

4. (Currently Amended) The method of claim 2, further comprising:

etching a hole into the substrate at a position other than a position of the first metal layer and the second metal layer;

depositing a third metal layer onto the substrate, the first metal layer, and the second metal layer;

applying an insulator onto the third metal layer;

~~etching a portion of the insulator at the position of the first metal layer and the second metal layer~~;

applying an organic semiconductor onto the third metal layer and the insulator; and

applying a sealing layer onto the organic semiconductor.

5-12. (Canceled)

13. (Previously Presented) The method of claim 4, further comprising making the third metal layer from gold.

14-18. (Canceled)

19. (Currently Amended) An electronic component with closely adjacent electrodes, comprising:

a substrate;

a first electrode on the substrate;

a second electrode on the substrate, wherein a separation between the first electrode and the second electrode is ~~between~~ about ten nanometers ~~and one hundred nanometers~~;

a third electrode in a hole in the substrate, wherein the third electrode is positioned within the separation between the first electrode and the second electrode;

an insulator on the third electrode;

an organic semiconductor on the first electrode, the second electrode, and the insulator; and

a sealing layer on the organic semiconductor.

20. (Previously Presented) The electronic component of claim 19, wherein the substrate comprises either a polymer film or a glass other than SiO_2.

21. (Previously Presented) The electronic component of claim 19, wherein the first electrode comprises either chromium or gold.

22. (Previously Presented) The electronic component of claim 19, wherein the third electrode comprises gold.

23. (Currently Amended) A device, comprising:

a first electrode on a substrate comprising a glass other than SiO_2;

a second electrode on the substrate and separated ~~between~~ about ten nanometers ~~and one hundred nanometers~~ from the first electrode;

a third electrode in a hole in the substrate, wherein the third electrode is positioned between the first electrode and the second electrode;

an insulator on the third electrode;

a semiconductor on the first electrode, the second electrode, and the insulator; and

a sealing layer on the semiconductor.

24. (Previously Presented) The electronic component of claim 23, wherein the first electrode comprises either chromium or gold.

25. (Previously Presented) The electronic component of claim 23, wherein the third electrode comprises gold.

26. (New) The method of claim 2, wherein said structuring comprises structuring the first photo lacquer on the surface of the first metal layer so that the first photo lacquer is in direct physical contact with the surface of the first metal layer.

27. (New) The electronic component of claim 19, wherein the first electrode and the second electrode are produced by:

forming a first metal layer on the substrate;

forming a photo lacquer on a first portion of the first metal layer;

etching a second portion of the first metal layer to expose a first portion of the substrate;

undercut etching the first metal layer to expose a second portion of the substrate so that an overhang is defined by the photo lacquer;

forming a second metal layer on the first portion of the substrate so that a space is defined between the overhang and the second portion of the substrate; and

removing the photo lacquer so that the first electrode comprises the first portion of the first metal layer and the second electrode comprises the second metal layer.

28. (New) The device of claim 23, wherein the first electrode and the second electrode are produced by:

forming a first metal layer on the substrate;

forming a photo lacquer on a first portion of the first metal layer;

etching a second portion of the first metal layer to expose a first portion of the substrate;

undercut etching the first metal layer to expose a second portion of the substrate so that an overhang is defined by the photo lacquer;

forming a second metal layer on the first portion of the substrate so that a space is defined between the overhang and the second portion of the substrate; and

removing the photo lacquer so that the first electrode comprises the first portion of the first metal layer and the second electrode comprises the second metal layer.